

Title (en)

HEAT-RECOVERABLE SOLDERING DEVICE.

Title (de)

WÄRMESCHRUMPFBARE LÖTVORRICHTUNG.

Title (fr)

DISPOSITIF THERMORECUPERABLE DE SOUDAGE.

Publication

EP 0449970 B1 19950301 (EN)

Application

EP 90901457 A 19891221

Priority

- US 8905763 W 19891221
- US 28833588 A 19881221

Abstract (en)

[origin: WO9007202A1] Heat recoverable soldering devices comprising a heat recoverable tubular article having at least one open end, and containing a solder insert, is provided with a curable adhesive insert between the solder insert and the open end. The curable adhesive melts, flows and cures when heat is applied to recover the article. The adhesive cures such that its viscosity increases to a value of at least 1.5 its initial viscosity during recovery of the article. Curing of the adhesive inhibits flow of the adhesive through the open end of the article and/or into the solder connection formed between two (or more) elongate bodies inserted into the article.

IPC 1-7

H01R 4/72; **B29C 61/06**

IPC 8 full level

B29C 61/06 (2006.01); **B29C 65/48** (2006.01); **C09J 127/12** (2006.01); **H01R 4/72** (2006.01)

CPC (source: EP)

H01R 4/723 (2013.01)

Designated contracting state (EPC)

AT BE CH DE ES FR GB IT LI NL SE

DOCDB simple family (publication)

WO 9007202 A1 19900628; AT E119320 T1 19950315; DE 68921492 D1 19950406; DE 68921492 T2 19951109; EP 0449970 A1 19911009; EP 0449970 B1 19950301; JP H04502381 A 19920423

DOCDB simple family (application)

US 8905763 W 19891221; AT 90901457 T 19891221; DE 68921492 T 19891221; EP 90901457 A 19891221; JP 50190389 A 19891221